

MULTI-PORT PRODUCTS

Ordering Information Package Description Table

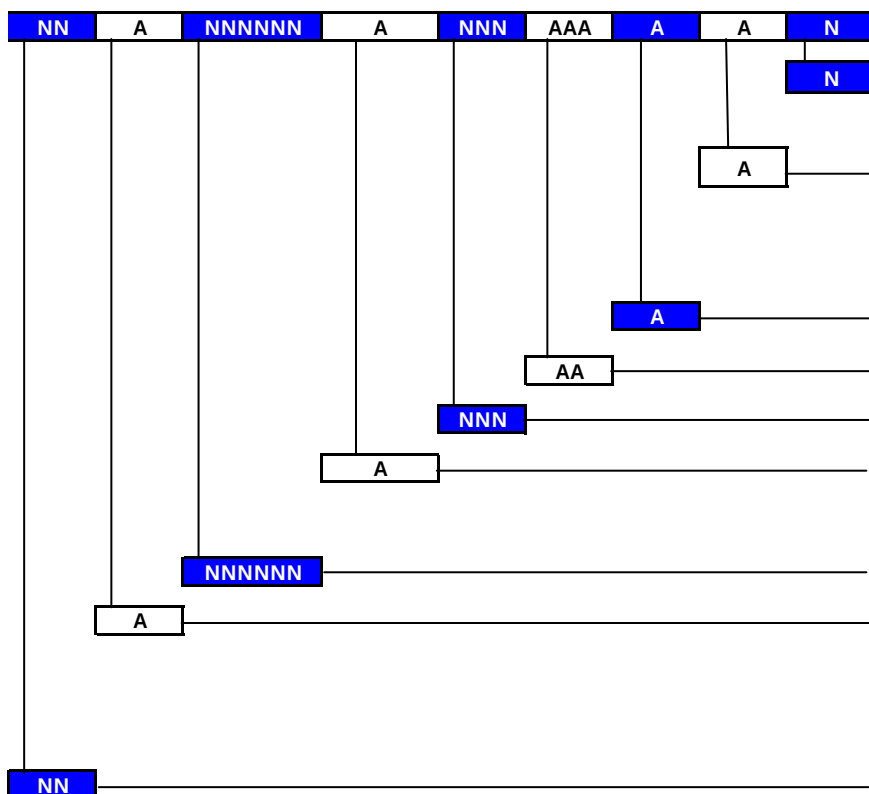
IDT ID	Abbr	Description	IDT ID	Abbr	Description
C	Sidebraz (SB)	Ceramic Dual In-line Package	BG	PBGA	Plastic Ball Grid Array
F	Flatpack	Ceramic Flat Package	P	PDIP	Plastic Dual In-line Package
CL	CLCC	Ceramic Leadless Chip Carrier	J	PLCC	Plastic Leaded Chip Carrier
L	LCC	Ceramic Leadless Chip Carrier	DR	PQFP	Plastic Quad Flat Package
G	CGA	Ceramic Pin Grid Array	PQF	PQFP	Plastic Quad Flat Package
BC	CABGA	Chip Array Ball Grid Array	DD	TQFP	Thin Quad Flat Package
BY	VCBGA	Chip Array Very Thin Ball Grid Array	PF	TQFP	Thin Quad Flat Package
BF	FPBGA	Fine Pitch Ball Grid Array	PRF	TQFP	Thin Quad Flat Package
G	PGA	Pin Grid Array	TF	TQFP	Thin Quad Flat Package

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Part Number Description

A = Alpha character

N = Numeric character



Shipping Type Optional 8 suffix at end of part number indicates Tape & Reel packaging

8 = Tape & Reel
Blank = Tube or Trays

Temperature

None: Commercial 0° C to +70° C
I: Industrial -40° C to +85° C
B: Military: -55° C to +125° C, compliant to MIL PRF 38535

Green None = Standard Packaging

G = Green packaging

Package See package description table above.

Speed Guaranteed minimum performance measured in nanoseconds or MHz

Power

S = Standard power
L = Low power

Device Type Refer to current datasheet

Voltage

None = 5.0 V
V = 3.3 V
T = 2.5 V
P = 1.8 V

Product Family

70
71